



Product Change Notification - KSRA-15IEHC532

Date:

16 Aug 2018

Product Category:

Ethernet PHYs

Affected CPNs:**Notification subject:**

CCB 3371 and 3371.001 Initial Notice: Qualification of ASE as a new assembly site for selected Micrel products available in 48L (7x7x0.09mm) and 64L (8x8x0.09mm) VQFN package.

Notification text:**PCN Status:**

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of ASE as a new assembly site for selected Micrel products available in 48L (7x7x0.9mm) and 64L (8x8x0.9mm) VQFN package.

Pre Change:

Assembled at TICIP assembly site

Post Change:

Assembled at ASE assembly site

Pre and Post Change Summary:

| | Pre Change | Post Change |
|---------------------------|--------------------------------|----------------|
| Assembly Site | Taiwan IC Packing Corp. (TICP) | ASE Inc. (ASE) |
| Wire material | Au | Au |
| Die attach material | EN4900 | EN4900 |
| Molding compound material | G631 | G631 |
| Lead frame material | C194 | C194 |

Impacts to Data Sheet:

None

Change Impact:

None.

Reason for Change:

To improve manufacturability by qualifying ASE as new assembly site

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:



October 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

| Workweek | May 2018 | | | | | --> | October 2018 | | | | |
|--------------------------|----------|----|----|----|----|-----|--------------|----|----|----|----|
| | 18 | 19 | 20 | 21 | 22 | | 40 | 41 | 42 | 43 | 44 |
| Initial PCN Issue Date | | | | X | | | | | | | |
| Qual Report Availability | | | | | | | | | | | X |
| Final PCN Issue Date | | | | | | | | | | | X |

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

May 21, 2018: Issued initial notification.

August 16, 2018: Re-issued initial notification to update affected CPN list by removing parts that uses Cu bond Wire.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-15IEHC532_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

KSZ9031MNXCA
KSZ9031MNXCA-TR
KSZ9031MNXIA
KSZ9031MNXIA-TR
KSZ9031RNXCA
KSZ9031RNXCA-TR
KSZ9031RNXIA
KSZ9031RNXIA-TR
KSZ9031RNXIA-TR-JDR